

# SOT1745-1

HBGA689, plastic, thermal enhanced ball grid array; 689 bumps; 1.0 mm pitch; 31 mm x 31 mm x 2.23 mm body

15 December 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	HBGA689
<b>Package type industry code</b>	HBGA689
<b>Package style descriptive code</b>	BGA (ball grid array)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	21-1-2016
<b>Manufacturer package code</b>	98ASA10737D

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	-	-	31	-	mm
E	package width	-	-	31	-	mm
A	seated height	-	-	2.23	2.46	mm
e	nominal pitch	-	-	1	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	689	-	



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## 2. Package outline

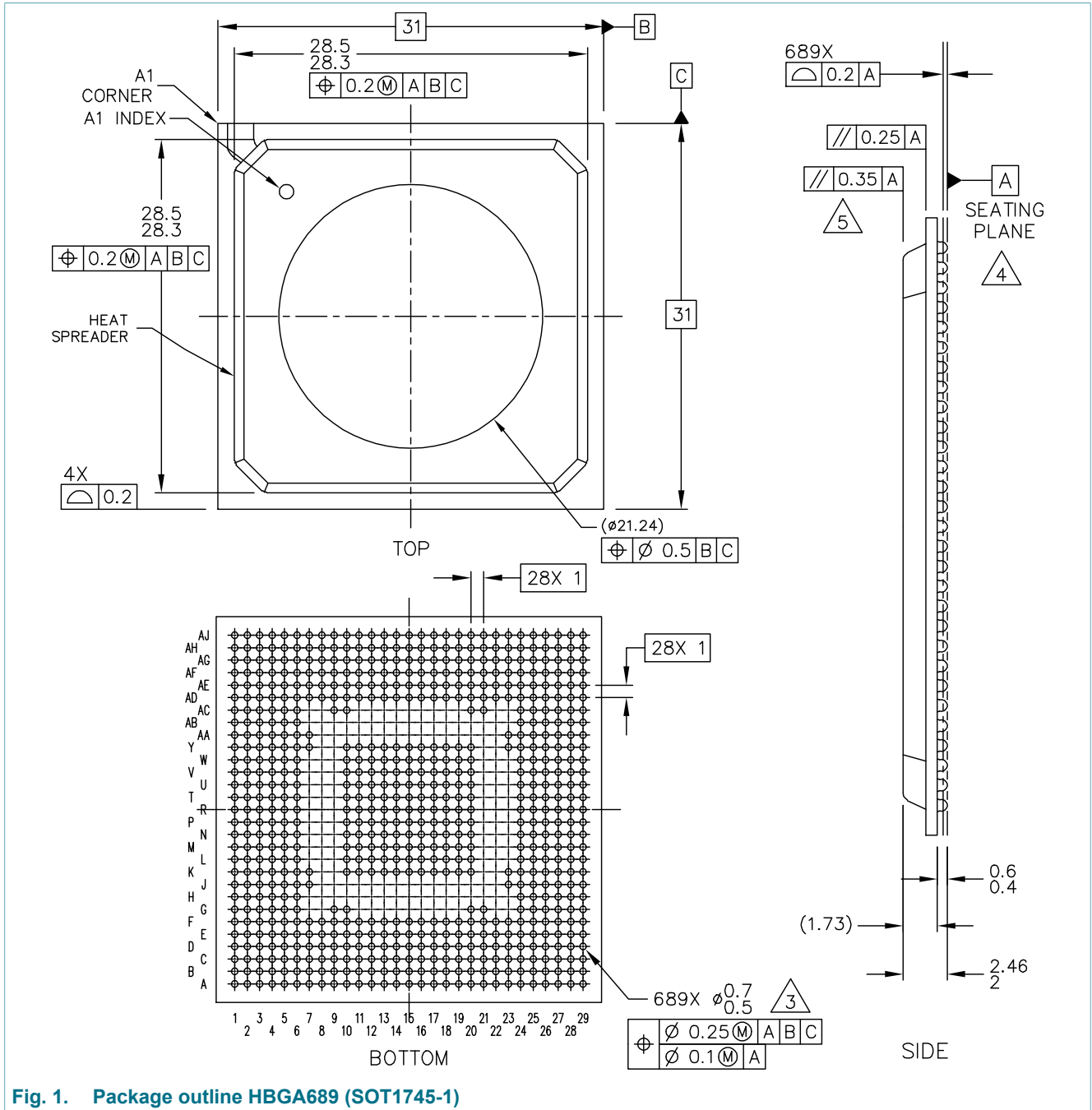


Fig. 1. Package outline HBGA689 (SOT1745-1)

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## NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

**Fig. 2. Package outline note HBGA689 (sot1745-1)**

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### 3. Legal information

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